




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H753XIH6	P2CV*450XXXV	A	9996	2018-12-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	368.67	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC105)	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	14x14x1.2	265	No lead	
Comment	Package : A07U TFBGA 14X14X1.2 P 0.8 240+25L DM00221013			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	P2CV*450XXXV				5.999999.0	1000002.0				
note : Substance present with less 0.001mg will not be declared in this document																
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	10.485	mg	supplier	die	Silicon (Si)	7440-21-3		9.743	mg	929232	26427				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	8393	239				
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	26323	749				
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	95	3				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	4292	122				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	763	22				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	95	3				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	30806	876				
				supplier	CORE	Glass Cloth	65997-17-3		12.471	mg	106100	33828				
				supplier	CORE	Epoxy resin	61788-97-4		9.721	mg	82700	26367				
SUBSTRATE (DS7409HGB)	M-011 Other inorganic materials	117.543	mg	supplier	CORE	Flame resistant epoxy resin	223769-10-6		2.939	mg	25000	7971				
				supplier	CORE	Heat resistant resin	25722-66-1		2.939	mg	25000	7971				
				supplier	CORE	Silica filler	7631-86-9		7.205	mg	61300	19544				
				supplier	CORE	Metal Hydroxide	Proprietary		0.588	mg	5000	1594				
				supplier	COPPER FOIL	Copper (Cu)	7440-50-8		26.506	mg	225500	71896				
				supplier	SOLDERMASK	Solvent naphtha(petroleum),heavy aromatic	64742-94-5		2.681	mg	22810	7273				
				supplier	SOLDERMASK	Napthalene	91-20-3		0.048	mg	410	131				
				supplier	SOLDERMASK	Phosinoxide derivative	Proprietary		0.247	mg	2100	670				
				supplier	SOLDERMASK	Talc containing no asbestiform fibers	14807-96-6		0.417	mg	3550	1132				
				supplier	SOLDERMASK	Barium sulfate	7727-43-7		1.267	mg	10780	3437				
				supplier	SOLDERMASK	Dipropylene glycol monomethyl ether	34590-94-8		1.158	mg	9850	3140				
				supplier	CU PLATING	Copper (Cu)	7440-50-8		29.186	mg	248300	79166				
				supplier	NI PLATING	Nickel (Ni)	7440-02-0		17.302	mg	147200	46932				
				supplier	AU PLATING	Gold (Au)	7440-57-5		2.868	mg	24400	7779				
				DIE ATTACH (2300)	M-011 Other inorganic materials	1.436	mg	supplier	GLUE	Silver (Ag)	7440-22-4		1.296	mg	903000	3517
								supplier	GLUE	Bismaleimide monomer	Proprietary		0.138	mg	96000	374
supplier	GLUE	Silane	Proprietary						0.001	mg	1000	4				
BONDING WIRE (MKE 4N)	M-011 Other inorganic materials	6.663	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		6.663	mg	1000000	18073				
SOLDERBALL (Sn98.5Ag0.1Cu0.5)	M-011 Other inorganic materials	43.673	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		43.018	mg	985002	116684				
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.437	mg	10006	1185				
				supplier	SOLDERBALL	Copper (Cu)	7440-50-8		0.218	mg	4992	591				
ENCAPSULATION (GE-100LFC5)	M-011 Other inorganic materials	188.870	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		169.909	mg	899607	460870				
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		8.533	mg	45177	23144				
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		7.584	mg	40157	20573				
				supplier	MOLDING COMPOUND	Metal Hydroxide	Proprietary		1.896	mg	10039	5143				
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.948	mg	5020	2572				